

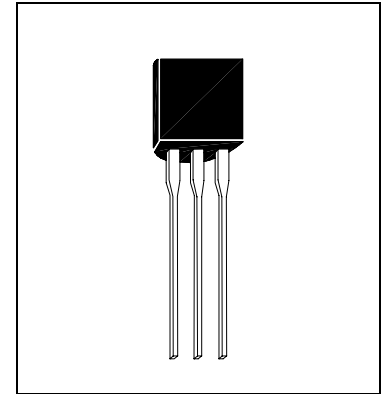


HSB764

PNP EPITAXIAL PLANAR TRANSISTOR

Description

Voltage regulator, Relay driver, electrical equipment application.



Absolute Maximum Ratings

- Maximum Temperatures
 Storage Temperature -55 ~ +150 °C
 Junction Temperature +150 °C Maximum
- Maximum Power Dissipation
 Total Power Dissipation (Ta=25°C) 900 mW
- Maximum Voltages and Currents (Ta=25°C)
 VCBO Collector to Base Voltage -60 V
 VCEO Collector to Emitter Voltage -50 V
 VEBO Emitter to Base Voltage -5 V
 IC Collector Current -1 A

Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-60			V	IC=-100uA, IE=0
BVCEO	-50			V	IC=-1mA, IB=0
BVEBO	-5			V	IE=-10uA, IC=0
ICBO			-1	uA	VCB=-50V, IE=0
IEBO			-1	uA	VEB=-4V, IC=0
*VCE(sat)			-700	mV	IC=-500mA, IB=-50mA
*VBE(sat)			-1.2	V	IC=-500mA, IB=-50mA
*hFE1	60		320		VCE=-2V, IC=-50mA
*hFE2	30				VCE=-2V, IC=-1A
fT		150		MHz	VCE=-10V, IC=-50mA
Cob		20		pF	VCB=-10V, IE=0, f=1MHz

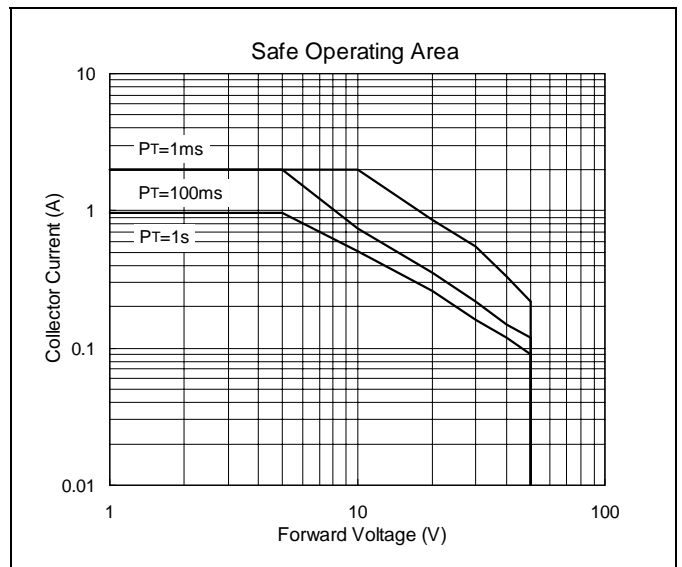
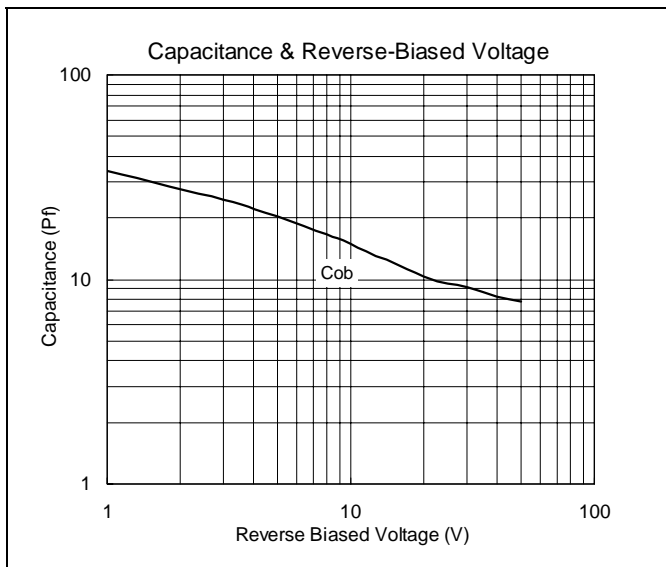
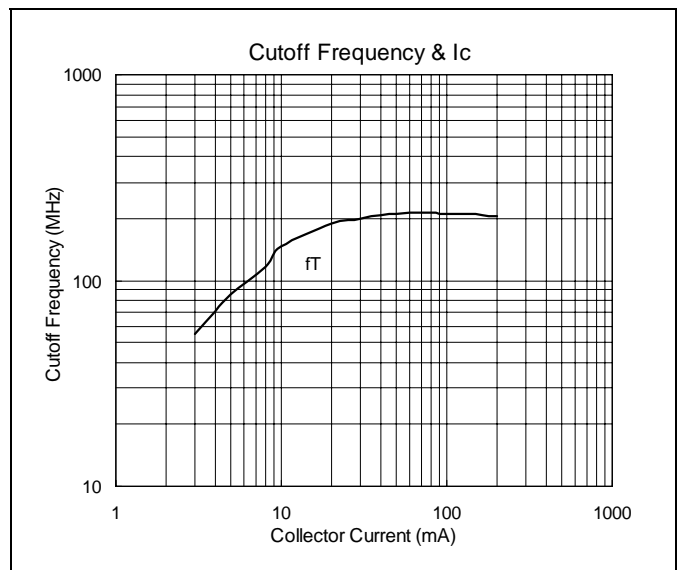
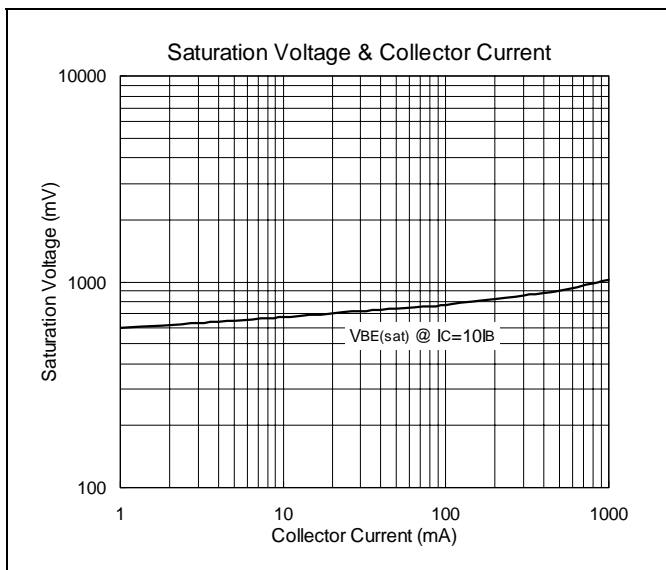
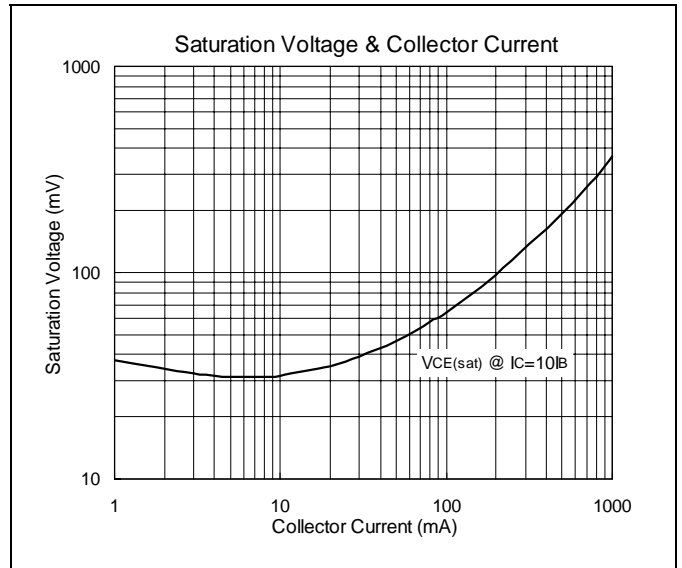
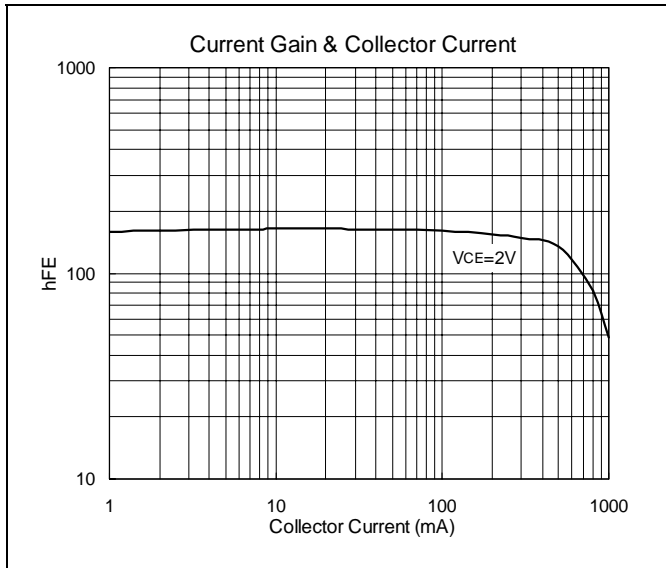
*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%

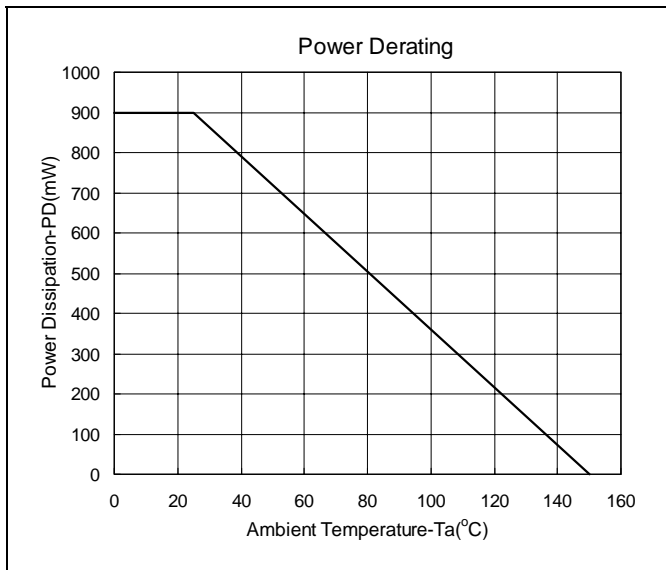
Classification of hFE1

Rank	D	E	F
Range	60-120	100-200	160-320



Characteristics Curve







TO-92 Dimension

3-Lead TO-92 Plastic Package
HSMC Package Code : A

Marking :

HSMC Logo → □ □ □ □ ← Product Series
 Part Number → □ □ □ □ □ □
 Date Code → □ □ □ □ □ □ ← Rank
 Laser Mark

HSMC Logo
 Product Series
 Part Number → □ □ □ □ □ □
 Ink Mark

Style : Pin 1. Emitter 2. Collector 3. Base

*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	α1	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	α2	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	α3	-	*2°	-	*2°

Notes : 1.Dimension and tolerance based on our Spec. dated Apr. 25,1996.
 2.Controlling dimension : millimeters.
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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